



OPA137 OPA2137 OPA4137

LOW COST FET-INPUT OPERATIONAL AMPLIFIERS *MicroAmplifier*™ Series

FEATURES

● FET INPUT: I_B = 5pA

● LOW OFFSET VOLTAGE: 1.5mV

● WIDE SUPPLY RANGE: ±2.25V to ±18V

● LOW QUIESCENT CURRENT: 220µA/channel

● EXCELLENT SPEED/POWER: 1MHz

INPUT TO POSITIVE SUPPLY

● MicroSIZE PACKAGES: SOT-23-5, MSOP-8

SINGLE, DUAL, AND QUAD

APPLICATIONS

- **STRAIN GAGE AMPLIFIER**
- PHOTODETECTOR AMPLIFIER
- PRECISION INTEGRATOR
- BATTERY-POWERED INSTRUMENTS
- TEST EQUIPMENT
- ACTIVE FILTERS

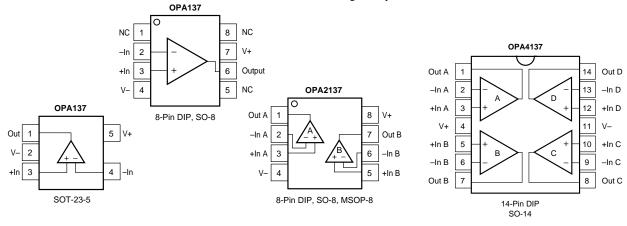
DESCRIPTION

OPA137 series FET-input operational amplifiers are designed for low cost and miniature applications. In addition to small size (SOT-23-5 and MSOP-8 packages), they provide low input bias current (5pA), low quiescent current (220μA/channel), and high open-loop gain (94dB).

Either single ($\pm 4.5V$ to $\pm 36V$) or dual (± 2.25 to $\pm 18V$) supplies can be used. The input common-mode voltage range includes the positive supply—suitable for many single-supply applications. Single, dual, and quad versions have identical specifications for maximum design flexibility.

OPA137 op amps are easy to use and free from phase inversion and overload problems found in some FET-input amplifiers. High performance, including linearity, is maintained as the amplifiers swing to their specified limits. In addition, the combination of high slew rate (3.5V/ μ s) and wide bandwidth (1MHz) provide fast settling time assuring good dynamic response. Dual and quad designs feature completely independent circuitry for lowest crosstalk and freedom from interaction.

The single (OPA137) packages are the tiny 5-lead SOT-23-5 surface mount, SO-8 surface mount, and 8-pin DIP. The dual (OPA2137) comes in the miniature MSOP-8 surface mount, SO-8 surface mount, and 8-pin DIP packages. The quad (OPA4137) packages are the SO-14 surface mount and the 14-pin DIP. All are specified from -40°C to +85°C and operate from -55°C to +125°C. A SPICE macromodel is available for design analysis.



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Internet: http://www.burr-brown.com/ • FAXLine: (800) 548-6133 (US/Canada Only) • Cable: BBRCORP • Telex: 066-6491 • FAX: (520) 889-1510 • Immediate Product Info: (800) 548-6132

SPECIFICATIONS: $V_S = \pm 15V$

At T_A = +25°C, R_L = 10k Ω connected to ground, unless otherwise noted. **Boldface** limits apply over the specified temperature range, T_A = -40°C to +85°C.

			OP	A137N, U A2137E, U PA4137U,	J, P	OPA	137NA, U 2137EA, U A4137UA	IA, PA	
PARAMETER		CONDITION	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
OFFSET VOLTAGE Input Offset Voltage T _A = -40°C to +85°C vs Temperature vs Power Supply T _A = -40°C to +85°C Channel Separation (dual, quad)	V _{OS} dV _{OS} /dT PSRR	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $V_S = \pm 3\text{V to } \pm 18\text{V}$ dc		±1.5 ±2.5 ±15 ±90	±3 ±7 ±250 ±250		±2.5 ±3.5 * *	±10 ± 15 *	mV mV μV/°C μV/V μV/V
INPUT BIAS CURRENT Input Bias Current vs Temperature Input Offset Current	I _B	$V_{CM} = 0V$	See	±5 Typical C ±2	±100 curve ±50		* * *	*	pA pA
NOISE Input Voltage Noise, f = 0.1 to 10Hz Input Voltage Noise Density, f = 1kH Current Noise Density, f = 1kHz				2 45 1.2			* * *		μVp-p nV/√Hz fA/√Hz
INPUT VOLTAGE RANGE Common-Mode Voltage Range Common-Mode Rejection Ratio OPA137, OPA2137 OPA4137 T _A = -40°C to +85°C OPA137, OPA2137 OPA4137	V _{CM} CMRR	$V_{CM} = -12V$ to 15V $V_{CM} = -12V$ to 15V	(V-) + 3 76 74 72 70	84 84	(V+)	* 70 70 70 70	*	*	V dB dB dB
INPUT IMPEDANCE Differential Common-Mode				10 ¹⁰ 1 10 ¹² 2			*		Ω pF Ω pF
OPEN-LOOP GAIN Open-Loop Voltage Gain T _A = -40°C to +85°C	A _{OL}	$V_O = -13.8V$ to 13.9V $V_O = -13.8V$ to 13.9V	86 86	94		*	*		dB dB
FREQUENCY RESPONSE Gain-Bandwidth Product Slew Rate Settling Time, 0.1% 0.01% Overload Recovery Time Total Harmonic Distortion + Noise	GBW SR THD+N	G = 1 $G = 1, 10V \text{ Step, } C_L = 100pF$ $G = 1, 10V \text{ Step, } C_L = 100pF$ $V_{IN} \cdot G = V_S$ G = 1, f = 1kHz, 3.5Vrms		1 3.5 8 10 1 0.05			* * * * *		MHz V/μs μs μs μs
OUTPUT Voltage Output T _A = -40°C to +85°C Short-Circuit Current Capacitive Load Drive	V _{OUT} I _{SC} C _{LOAD}		(V-) + 1.2 (V-) + 1.2	-25/+60 1000	(V+) - 1.1 (V+) - 1.1	*	*	*	V V mA pF
POWER SUPPLY Specified Operating Range Operating Voltage Range Dual Supplies Single Supply Quiescent Current T _A = -40°C to +85°C	V _S	I _O = 0 I _O = 0	±2.25 ⁽¹⁾ +4.5	±15	±18 +36 ±270 ± 375	*	*	* * *	V V V μA μA
TEMPERATURE RANGE Specified Range Operating Range Storage Range Thermal Resistance SOT-23-5 Surface Mount MSOP-8 Surface Mount SO-8 Surface Mount 8-Pin DIP SO-14 Surface Mount 14-Pin DIP	$ heta_{ m JA}$	-	-40 -55 -55	200 150 150 100 100 80	+85 +125 +125	* * *	* * * * * * *	* *	

^{*} Specifications the same as OPA137N, U, P.

NOTE: (1) At minimum power supply voltage inputs must be biased above ground in accordance with common-mode voltage range restrictions—see "Operating Voltage" discussion.



ABSOLUTE MAXIMUM RATINGS(1)

Supply Voltage, V+ to V	36V
Input Voltage	(V–) –0.7V to (V+) +0.7V
Input Current	2mA
Output Short-Circuit ⁽²⁾	
Operating Temperature	55°C to +125°C
Storage Temperature	55°C to +125°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	300°C
,	

NOTE: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum ratings for extended periods may affact device reliability. (2) Short circuit to ground, one amplifier per package.



This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION

PRODUCT	PACKAGE	PACKAGE DRAWING NUMBER ⁽¹⁾	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER ⁽²⁾	TRANSPORT MEDIA
Single						
OPA137N	5-Lead SOT-23-5 Surface Mount	331	-40°C to +85°C	E37 ⁽³⁾	OPA137N/250 OPA137N/3K	Tape and Reel Tape and Reel
OPA137NA	5-Lead SOT-23-5 Surface Mount	331	-40°C to +85°C	E37 ⁽³⁾	OPA137NA/250	Tape and Reel
OPA137U	SO-8 Surface Mount	182	-40°C to +85°C	OPA137U	OPA137NA/3K OPA137U	Tape and Reel Rails
OPA137UA	SO-8 Surface Mount	182	-40°C to +85°C	OPA137UA	OPA137U/2K5 OPA137UA	Tape and Reel Rails
" OPA137P	" 8-Pin DIP	006	" -40°C to +85°C	" OPA137P	OPA137UA/2K5 OPA137P	Tape and Reel Rails
OPA137PA	8-Pin DIP	006	-40°C to +85°C	OPA137PA	OPA137PA	Rails
Dual						
OPA2137E	MSOP-8 Surface Mount	337	-40°C to +85°C	E37 ⁽³⁾	OPA2137E/250 OPA2137E/2K5	Tape and Reel Tape and Reel
OPA2137EA	MSOP-8 Surface Mount	337	-40°C to +85°C	E37 ⁽³⁾	OPA2137EA/250 OPA2137EA/2K5	Tape and Reel Tape and Reel
OPA2137U	SO-8 Surface Mount	182	-40°C to +85°C	OPA2137U	OPA2137U OPA2137U OPA2137U/2K5	Rails
OPA2137UA	SO-8 Surface Mount	182	-40°C to +85°C	OPA2137UA	OPA2137UA	Tape and Reel Rails
OPA2137P	8-Pin DIP	006	-40°C to +85°C	OPA2137P	OPA2137UA/2K5 OPA2137P	Tape and Reel Rails
OPA2137PA	8-Pin DIP	006	-40°C to +85°C	OPA2137PA	OPA2137PA	Rails
Quad OPA4137U	SO-14 Surface Mount	235	–40°C to +85°C	OPA4137U	OPA4137U	Rails
"	"	200	40 0 10 100 0	017(41070	OPA4137U/2K5	Tape and Reel
OPA4137UA "	SO-14 Surface Mount	235	-40°C to +85°C	OPA4137UA "	OPA4137UA OPA4137UA/2K5	Rails Tape and Reel
OPA4137P	14-Pin DIP	010	-40°C to +85°C	OPA4137P	OPA4137P	Rails
OPA4137PA	14-Pin DIP	010	-40°C to +85°C	OPA4137PA	OPA4137PA	Rails

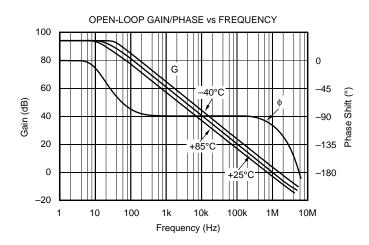
NOTES: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix C of Burr-Brown IC Data Book. (2) Models with a slash (/) are available only in Tape and Reel in the quantities indicated (e.g., /2K5 indicates 2500 devices per reel). Ordering 3000 pieces of "OPA137NA/3K" will get a single 3000-piece Tape and Reel. For detailed Tape and Reel mechanical information, refer to Appendix B of Burr-Brown IC Data Book. (3) Grade information is marked on the reel.

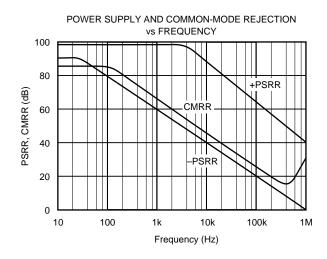
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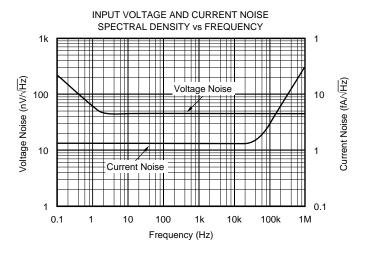


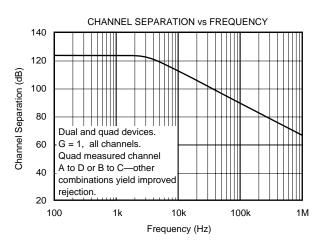
TYPICAL PERFORMANCE CURVES

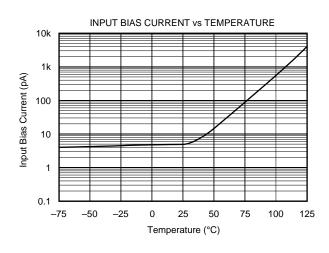
At T_A = +25°C, V_S = ±15V, R_L = 10k Ω , connected to ground, unless otherwise noted.

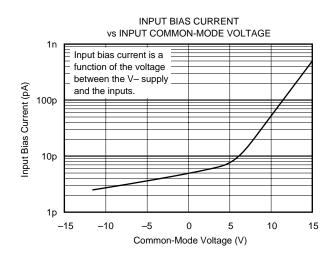






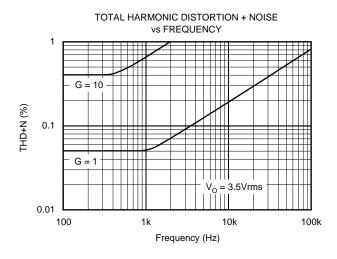


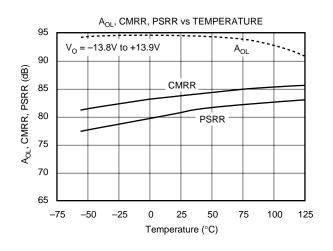


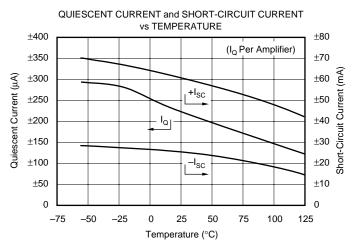


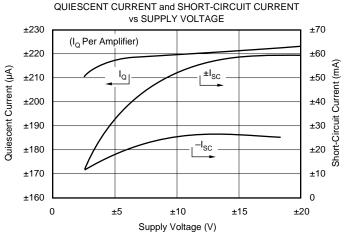
TYPICAL PERFORMANCE CURVES (CONT)

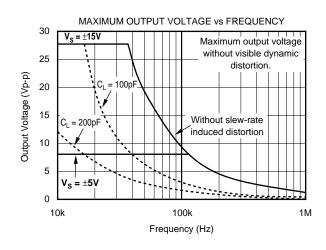
At T_A = +25°C, V_S = ±15V, R_L = 10k Ω , connected to ground, unless otherwise noted.

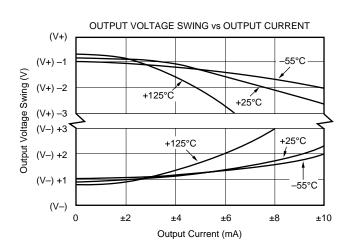






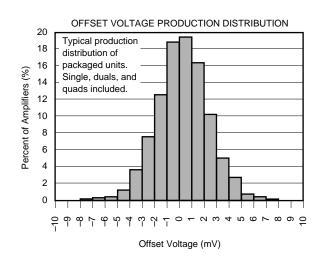


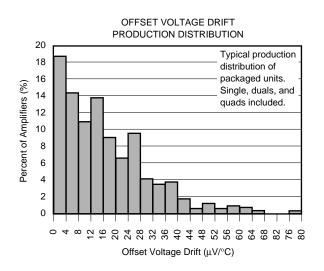


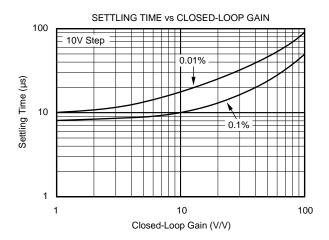


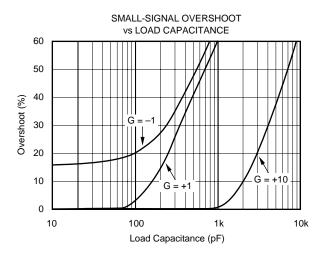
TYPICAL PERFORMANCE CURVES (CONT)

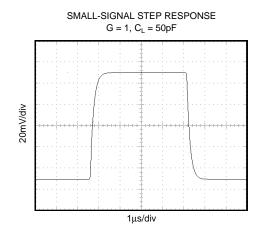
At T_A = +25°C, V_S = ±15V, R_L = 10k Ω , connected to ground, unless otherwise noted.

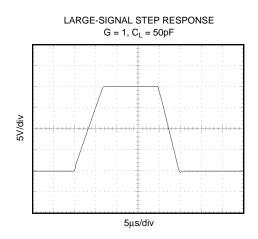












APPLICATIONS INFORMATION

OPA137 series op amps are unity-gain stable and suitable for a wide range of general-purpose applications. Power supply pins should be bypassed with 10nF ceramic capacitors or larger. All circuitry is completely independent in dual and quad versions, assuring normal performance when one amplifier in a package is overdriven or short circuited. Many key parameters are guaranteed over the specified temperature range, -40° C to $+85^{\circ}$ C.

OPERATING VOLTAGE

OPA137 op amps can be operated on power supplies as low as ± 2.25 V. Performance remains excellent with power supplies ranging from ± 2.25 V to ± 18 V (± 4.5 V to ± 36 V single supply). Most parameters vary only slightly throughout this supply voltage range. Quiescent current and short-circuit current vs supply voltage are shown in Typical Performance Curves.

Operation at very low supply voltage ($V_S \le \pm 3V$) requires careful attention to ensure that the common-mode voltage remains within the linear range, $V_{CM} = (V-)+3V$ to (V+). Inputs may need to be biased above ground in accordance with the common-mode voltage range restrictions for linear operation.

INPUT VOLTAGE

The input common-mode voltage range of OPA137 series op amps extends from (V–)+3V to the positive rail, V+. For normal operation, inputs should be limited to this range. The inputs may go beyond the power supplies without output phase-reversal. Many FET-input op amps (such as TL061 types) exhibit phase-reversal of the output when the input common-mode range is exceeded. This can occur in voltage-follower circuits, causing serious problems in control loop applications.

Input terminals are diode-clamped to the power supply rails for ESD protection. If the input voltage can exceed the negative supply by 500mV, input current should be limited to 2mA (or less). If the input current is not adequately limited, you may see unpredicatable behavior in the other amplifiers in the package. This is easily accomplished with an input resistor as shown in Figure 1. Many input signals are inherently current-limited, therefore, a limiting resistor may not be required.

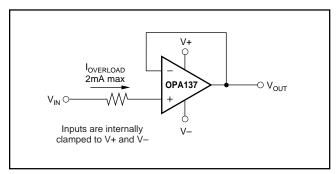


FIGURE 1. Input Current Protection for Voltages Exceeding the Supply Voltage.

HIGH-SIDE CURRENT SENSING

Many applications require the sensing of signals near the positive supply. The common-mode input range of OPA137 op amps includes the positive rail, enabling them to be used to sense power supply currents as shown in Figure 2.

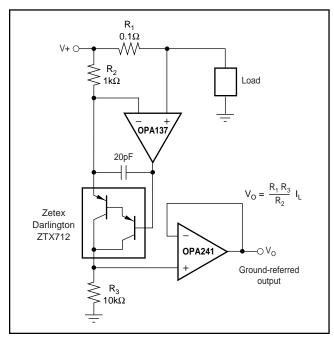


FIGURE 2. High-Side Current Monitor.

INPUT BIAS CURRENT

The input bias current is approximately 5pA at room temperature and increases with temperature as shown in the typical performance curve "Input Bias Current vs Temperature."

Input Bias current also varies with common-mode voltage and power supply voltage. This variation is dependent on the voltage between the negative power supply and the common-mode input voltage. The effect is shown in the typical performance curve "Input Bias Current vs Common-Mode Voltage."

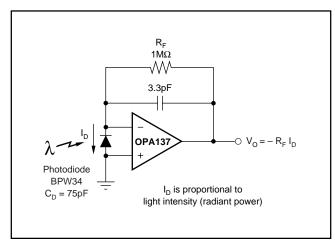


FIGURE 3. Photodetector Amplifier.



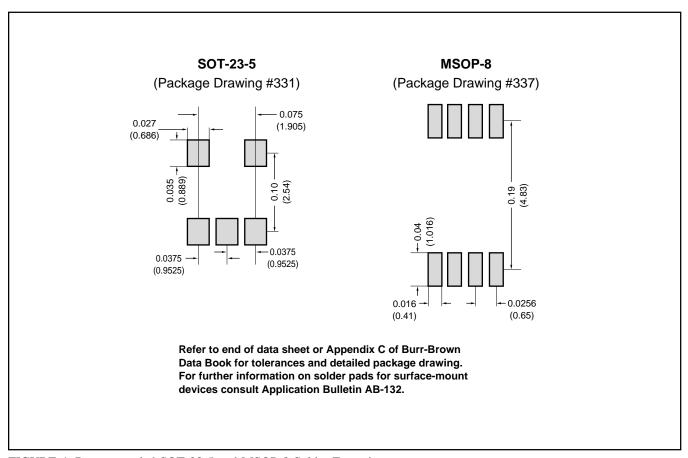


FIGURE 4. Recommended SOT-23-5 and MSOP-8 Solder Footprints.





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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	_		Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)				Qty	(2)	(6)	(3)		(4/5)	
OPA137N/250	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		E37	Samples
OPA137N/250E4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		E37	Samples
OPA137N/3K	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		E37	Samples
OPA137N/3KE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		E37	Samples
OPA137NA/250	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		E37	Samples
OPA137NA/250E4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		E37	Samples
OPA137NA/3K	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		E37	Samples
OPA137P	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU SNPB	N / A for Pkg Type		OPA137P	Samples
OPA137PA	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU SNPB	N / A for Pkg Type		OPA137P A	Samples
OPA137U	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		OPA 137U	Samples
OPA137UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		OPA 137U A	Samples
OPA137UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		OPA 137U A	Samples
OPA137UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		OPA 137U A	Samples
OPA137UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		OPA 137U A	Samples
OPA137UE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		OPA 137U	Samples





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
OPA2137E/250	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU Call TI	Level-3-260C-168 HR	-40 to 85	E37	Sample
OPA2137E/250G4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR -40 to 85		E37	Sample
OPA2137E/2K5	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU Call TI	Level-3-260C-168 HR	-40 to 85	E37	Sample
OPA2137E/2K5G4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	E37	Sample
OPA2137EA/250	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU Call TI	Level-3-260C-168 HR		E37	Sample
OPA2137EA/250G4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		E37	Sample
OPA2137EA/2K5	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU Call TI	Level-3-260C-168 HR		E37	Sample
OPA2137P	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		OPA2137P	Sampl
OPA2137PA	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		OPA2137P A	Sampl
OPA2137PAG4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		OPA2137P A	Sampl
OPA2137PG4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		OPA2137P	Sampl
OPA2137U	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		OPA 2137U	Sampl
OPA2137U/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		OPA 2137U	Sampl
OPA2137UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR -40 to 85		OPA 2137U A	Sample
OPA2137UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR -40 to 85		OPA 2137U A	Sampl
OPA2137UA/2K5E4	PREVIEW	SOIC	D	8		TBD	Call TI	Call TI	-40 to 85		
OPA2137UAE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA 2137U A	Samp



PACKAGE OPTION ADDENDUM

10-Jun-2014

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
OPA2137UE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		OPA 2137U	Samples
OPA4137P	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		OPA4137P	Samples
OPA4137PA	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		OPA4137P A	Samples
OPA4137PAG4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		OPA4137P A	Samples
OPA4137U	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA4137U	Samples
OPA4137U/2K5	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA4137U	Samples
OPA4137UA	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA4137U A	Samples
OPA4137UA/2K5	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA4137U A	Samples
OPA4137UAE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA4137U A	Samples
OPA4137UAG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	OPA4137U A	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

10-Jun-2014

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION



TAPE DIMENSIONS KO P1 BO W Cavity AO

_		
		Dimension designed to accommodate the component width
		Dimension designed to accommodate the component length
		Dimension designed to accommodate the component thickness
	W	Overall width of the carrier tape
ſ	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA137N/250	SOT-23	DBV	5	250	178.0	8.4	3.3	3.2	1.4	4.0	8.0	Q3
OPA137N/3K	SOT-23	DBV	5	3000	178.0	8.4	3.3	3.2	1.4	4.0	8.0	Q3
OPA137NA/250	SOT-23	DBV	5	250	178.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
OPA137NA/3K	SOT-23	DBV	5	3000	178.0	8.4	3.3	3.2	1.4	4.0	8.0	Q3
OPA137UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA2137E/250	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2137E/2K5	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2137EA/250	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2137EA/2K5	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2137U/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA2137UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA4137U/2K5	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
OPA4137UA/2K5	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA137N/250	SOT-23	DBV	5	250	565.0	140.0	75.0
OPA137N/3K	SOT-23	DBV	5	3000	565.0	140.0	75.0
OPA137NA/250	SOT-23	DBV	5	250	565.0	140.0	75.0
OPA137NA/3K	SOT-23	DBV	5	3000	565.0	140.0	75.0
OPA137UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA2137E/250	VSSOP	DGK	8	250	210.0	185.0	35.0
OPA2137E/2K5	VSSOP	DGK	8	2500	367.0	367.0	35.0
OPA2137EA/250	VSSOP	DGK	8	250	210.0	185.0	35.0
OPA2137EA/2K5	VSSOP	DGK	8	2500	367.0	367.0	35.0
OPA2137U/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA2137UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA4137U/2K5	SOIC	D	14	2500	367.0	367.0	38.0
OPA4137UA/2K5	SOIC	D	14	2500	367.0	367.0	38.0

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